- 2-V to 6-V VCC Operation ('HC190, 191)
- $4.5-\mathrm{V}$ to $5.5-\mathrm{V} \mathrm{V}_{\mathrm{CC}}$ Operation ('HCT191)
- Wide Operating Temperature Range of $-55^{\circ} \mathrm{C}$ to $125^{\circ} \mathrm{C}$
- Synchronous Counting and Asynchronous Loading
- Two Outputs for n-Bit Cascading
- Look-Ahead Carry for High-Speed Counting
- Balanced Propagation Delays and Transition Times
- Standard Outputs Drive Up To 15 LS-TTL Loads
- Significant Power Reduction Compared to LS-TTL Logic ICs


## description/ordering information

The CD54/74HC190 are asynchronously presettable BCD decade counters, whereas the CD54/74HC191 and CD54/74HCT191 are asynchronously presettable binary counters.

Presetting the counter to the number on preset data inputs (A-D) is accomplished by a low asynchronous parallel load ( $\overline{\text { LOAD }}$ ) input. Counting occurs when $\overline{\text { LOAD }}$ is high, count enable ( $\overline{C T E N}$ ) is low, and the down/up (D/ $\overline{\mathrm{U}}$ ) input is either high for down counting or low for up counting. The counter is decremented or incremented synchronously with the low-to-high transition of the clock.

ORDERING INFORMATION

| $\mathrm{T}_{\mathrm{A}}$ | PACKAGE $\dagger$ |  | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
| :---: | :---: | :---: | :---: | :---: |
| $-55^{\circ} \mathrm{C}$ to $125^{\circ} \mathrm{C}$ | PDIP - E | Tube of 25 | CD74HC190E | CD74HC190E |
|  |  |  | CD74HC191E | CD74HC191E |
|  |  |  | CD74HCT191E | CD74HCT191E |
|  | SOIC - M | Tube of 40 | CD74HC191M | HC191M |
|  |  | Reel of 2500 | CD74HC191M96 |  |
|  |  | Reel of 250 | CD74HC191MT |  |
|  |  | Tube of 40 | CD74HCT191M | HCT191M |
|  | SOP - NS | Reel of 2000 | CD74HC190NSR | HC190M |
|  | TSSOP - PW | Tube of 90 | CD74HC190PW | HJ190 |
|  |  | Reel of 2000 | CD74HC190PWR |  |
|  |  | Reel of 250 | CD74HC190PWT |  |
|  | CDIP - F | Tube of 25 | CD54HC190F3A | CD54HC190F3A |
|  |  |  | CD54HC191F3A | CD54HC191F3A |
|  |  |  | CD54HCT191F3A | CD54HCT191F3A |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

## description/ordering information (continued)

When an overflow or underflow of the counter occurs, the MAX/MIN output, which is low during counting, goes high and remains high for one clock cycle. This output can be used for look-ahead carry in high-speed cascading (see Figure 1). The MAX/MIN output also initiates the ripple clock ( $\overline{\mathrm{RCO}}$ ) output, which normally is high, goes low, and remains low for the low-level portion of the clock pulse. These counters can be cascaded using $\overline{\mathrm{RCO}}$ (see Figure 2).
If a decade counter is preset to an illegal state or assumes an illegal state when power is applied, it returns to the normal sequence in one or two counts, as shown in the state diagrams (see Figure 3).
FUNCTION TABLE

| INPUTS |  |  |  | FUNCTION |
| :---: | :---: | :---: | :---: | :--- |
| $\overline{\text { LOAD }}$ | $\overline{\text { CTEN }}$ | D/ $\overline{\mathbf{U}}$ | CLK |  |
| H | L | L | $\zeta$ | Count up |
| H | L | H | $\zeta$ | Count down |
| L | X | X | X | Asynchronous preset |
| H | H | X | X | No change |

[^0]

CD54HC190, CD74HC190
CD54HC191, CD74HC191, CD54HCT191, CD74HCT191

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'HC190 logic diagram (continued)

'HC191, 'HCT191 logic diagram

'HC191, 'HCT191 logic diagram (continued)

'HC190 and 'HC191/HCT191 flip-flop


## typical load, count, and inhibit sequence for 'HC190

The following sequence is illustrated below:

1. Load (preset) to BCD 7
2. Count up to 8,9 (maximum), 0, 1, and 2
3. Inhibit
4. Count down to 1,0 (minimum), 9,8 , and 7

typical load, count, and inhibit sequence for 'HC191 and 'HCT191
The following sequence is illustrated below:
5. Load (preset) to binary 13
6. Count up to 14,15 (maximum), 0,1 , and 2
7. Inhibit
8. Count down to 1,0 (minimum), 15,14 , and 13



Figure 1. 'HC190 Synchronous n-Stage Counter With Parallel Gated Terminal Count


Figure 2. 'HC191, 'HCT191 Synchronous n-Stage Counter With Parallel Gated Terminal Count


Count Up
NOTE: Illegal states in BCD counters corrected in one count


Count Down
NOTE: Illegal states in BCD counters corrected in one or two counts

Figure 3. 'HC190 State Diagram

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted) $\dagger$

$$
\begin{aligned}
& \text { Input clamp current, } \mathrm{I}_{\mathrm{IK}}\left(\mathrm{~V}_{1}<0 \text { or } \mathrm{V}_{1}>\mathrm{V}_{\mathrm{CC}} \text { ) (see Note 1) .......................................... } \pm 20 \mathrm{~mA}\right.
\end{aligned}
$$

$$
\begin{aligned}
& \text { Continuous output source or sink current per output, } \mathrm{IO}_{\mathrm{O}}\left(\mathrm{~V}_{\mathrm{O}}=0 \text { to } \mathrm{V}_{\mathrm{CC}}\right) \ldots \ldots \ldots \ldots \ldots \ldots \ldots \ldots . \ldots 25 \mathrm{~mA} \\
& \text { Continuous current through } \mathrm{V}_{\mathrm{CC}} \text { or GND . .......................................................... } \pm 50 \mathrm{~mA} \\
& \text { Package thermal impedance, } \theta_{\mathrm{JA}} \text { (see Note 2): E package ......................................... } 67^{\circ} \mathrm{C} / \mathrm{W} \\
& \text { M package ......................................... } 73^{\circ} \mathrm{C} / \mathrm{W} \\
& \text { NS package ....................................... } 64^{\circ} \mathrm{C} / \mathrm{W} \\
& \text { PW package ........................................ } 108^{\circ} \mathrm{C} / \mathrm{W} \\
& \text { Storage temperature range, } \mathrm{T}_{\text {stg }} \\
& \dagger \text { Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and } \\
& \text { functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not } \\
& \text { implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. } \\
& \text { NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed. } \\
& \text { 2. The package thermal impedance is calculated in accordance with JESD 51-7. }
\end{aligned}
$$

recommended operating conditions for 'HC190 and 'HC191 (see Note 3)

|  |  |  | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ |  | $\begin{gathered} \mathrm{T}_{\mathrm{A}}=-55^{\circ} \mathrm{C} \\ \mathrm{TO} 125^{\circ} \mathrm{C} \end{gathered}$ |  | $\begin{gathered} \mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C} \\ \mathrm{TO} 85^{\circ} \mathrm{C} \end{gathered}$ |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | MIN | MAX | MIN | MAX | MIN | MAX |  |
| $\mathrm{V}_{\mathrm{CC}}$ | Supply voltage |  | 2 | 6 | 2 | 6 | 2 | 6 | V |
| $\mathrm{V}_{\mathrm{IH}}$ | High-level input voltage | $\mathrm{V}_{\mathrm{CC}}=2 \mathrm{~V}$ | 1.5 |  | 1.5 |  | 1.5 |  | V |
|  |  | $\mathrm{V}_{\mathrm{CC}}=4.5 \mathrm{~V}$ | 3.15 |  | 3.15 |  | 3.15 |  |  |
|  |  | $\mathrm{V}_{\mathrm{CC}}=6 \mathrm{~V}$ | 4.2 |  | 4.2 |  | 4.2 |  |  |
| VIL | Low-level input voltage | $\mathrm{V}_{\mathrm{CC}}=2 \mathrm{~V}$ |  | 0.5 |  | 0.5 |  | 0.5 | V |
|  |  | $\mathrm{V}_{\mathrm{CC}}=4.5 \mathrm{~V}$ |  | 1.35 |  | 1.35 |  | 1.35 |  |
|  |  | $\mathrm{V}_{\mathrm{CC}}=6 \mathrm{~V}$ |  | 1.8 |  | 1.8 |  | 1.8 |  |
| $\mathrm{V}_{1}$ | Input voltage |  | 0 | $\mathrm{V}_{\mathrm{CC}}$ | 0 | $\mathrm{V}_{\mathrm{CC}}$ | 0 | $\mathrm{V}_{\mathrm{CC}}$ | V |
| $\mathrm{V}_{\mathrm{O}}$ | Output voltage |  | 0 | $\mathrm{V}_{\mathrm{CC}}$ | 0 | $\mathrm{V}_{\mathrm{CC}}$ | 0 | $\mathrm{V}_{\mathrm{CC}}$ | V |
| $t_{t}$ | Input transition (rise and fall) time | $\mathrm{V}_{\mathrm{CC}}=2 \mathrm{~V}$ |  | 1000 |  | 1000 |  | 1000 | ns |
|  |  | $\mathrm{V}_{\mathrm{CC}}=4.5 \mathrm{~V}$ |  | 500 |  | 500 |  | 500 |  |
|  |  | $\mathrm{V}_{\mathrm{CC}}=6 \mathrm{~V}$ |  | 400 |  | 400 |  | 400 |  |

NOTE 3: All unused inputs of the device must be held at $\mathrm{V}_{\mathrm{CC}}$ or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.
recommended operating conditions for 'HCT191 (see Note 4)

|  |  | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ |  | $\begin{gathered} \mathrm{T}_{\mathrm{A}}=-55^{\circ} \mathrm{C} \\ \mathrm{TO} 125^{\circ} \mathrm{C} \end{gathered}$ |  | $\begin{gathered} \mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C} \\ \mathrm{TO} 85^{\circ} \mathrm{C} \end{gathered}$ |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | MIN | MAX | MIN | MAX | MIN | MAX |  |
| $\mathrm{V}_{\mathrm{CC}}$ | Supply voltage | 4.5 | 5.5 | 4.5 | 5.5 | 4.5 | 5.5 | V |
| $\mathrm{V}_{\text {IH }}$ | High-level input voltage | 2 |  | 2 |  | 2 |  | V |
| $\mathrm{V}_{\text {IL }}$ | Low-level input voltage |  | 0.8 |  | 0.8 |  | 0.8 | V |
| $\mathrm{V}_{1}$ | Input voltage |  | $\mathrm{V}_{\mathrm{CC}}$ |  | $\mathrm{V}_{\mathrm{CC}}$ |  | $\mathrm{V}_{\mathrm{CC}}$ | V |
| $\mathrm{V}_{\mathrm{O}}$ | Output voltage |  | $\mathrm{V}_{\mathrm{CC}}$ |  | $\mathrm{V}_{\text {CC }}$ |  | $\mathrm{V}_{\text {CC }}$ | V |
| $\mathrm{t}_{\mathrm{t}}$ | Input transition (rise and fall) time |  | 500 |  | 500 |  | 500 | ns |

NOTE 4: All unused inputs of the device must be held at $\mathrm{V}_{\mathrm{CC}}$ or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.
'HC190, 'HC191
electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS |  | Vcc | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ |  | $\begin{gathered} \mathrm{T}_{\mathrm{A}}=-55^{\circ} \mathrm{C} \\ \mathrm{TO} 125^{\circ} \mathrm{C} \end{gathered}$ |  | $\begin{gathered} \mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C} \\ \mathrm{TO} 85^{\circ} \mathrm{C} \end{gathered}$ |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | MIN | MAX | MIN | MAX | MIN | MAX |  |
| $\mathrm{V}_{\mathrm{OH}}$ | $\mathrm{V}_{\mathrm{I}}=\mathrm{V}_{\text {IH }}$ or $\mathrm{V}_{\text {IL }}$ | $\mathrm{IOH}=-20 \mu \mathrm{~A}$ |  | 2 V | 1.9 |  | 1.9 |  | 1.9 |  | V |
|  |  |  | 4.5 V | 4.4 |  | 4.4 |  | 4.4 |  |  |  |
|  |  |  | 6 V | 5.9 |  | 5.9 |  | 5.9 |  |  |  |
|  |  | $\mathrm{IOH}=-4 \mathrm{~mA}$ | 4.5 V | 3.98 |  | 3.7 |  | 3.84 |  |  |  |
|  |  | $\mathrm{IOH}=-5.2 \mathrm{~mA}$ | 6 V | 5.48 |  | 5.2 |  | 5.34 |  |  |  |
| VOL | $\mathrm{V}_{\mathrm{I}}=\mathrm{V}_{\text {IH }}$ or $\mathrm{V}_{\text {IL }}$ | l OL $=20 \mu \mathrm{~A}$ | 2 V |  | 0.1 |  | 0.1 |  | 0.1 | V |  |
|  |  |  | 4.5 V |  | 0.1 |  | 0.1 |  | 0.1 |  |  |
|  |  |  | 6 V |  | 0.1 |  | 0.1 |  | 0.1 |  |  |
|  |  | $\mathrm{l} \mathrm{OL}=4 \mathrm{~mA}$ | 4.5 V |  | 0.26 |  | 0.4 |  | 0.33 |  |  |
|  |  | $\mathrm{IOL}=5.2 \mathrm{~mA}$ | 6 V |  | 0.26 |  | 0.4 |  | 0.33 |  |  |
| 1 | $\mathrm{V}_{\mathrm{I}}=\mathrm{V}_{\mathrm{CC}}$ or 0 |  | 6 V |  | $\pm 0.1$ |  | $\pm 1$ |  | $\pm 1$ | $\mu \mathrm{A}$ |  |
| ICC | $\mathrm{V}_{\mathrm{I}}=\mathrm{V}_{\text {CC }}$ or 0 , | $\mathrm{I}=0$ | 6 V |  | 8 |  | 160 |  | 80 | $\mu \mathrm{A}$ |  |
| $\mathrm{C}_{\mathrm{i}}$ |  |  |  |  | 10 |  | 10 |  | 10 | pF |  |

## 'HCT191

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS |  | $\mathrm{V}_{\mathrm{CC}}$ | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ |  |  | $\begin{gathered} \mathrm{T}_{\mathrm{A}}=-55^{\circ} \mathrm{C} \\ \mathrm{TO} 125^{\circ} \mathrm{C} \end{gathered}$ |  | $\begin{gathered} \mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C} \\ \mathrm{TO} 85^{\circ} \mathrm{C} \end{gathered}$ |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | MIN | TYP | MAX | MIN | MAX | MIN | MAX |  |
| $\mathrm{V}_{\mathrm{OH}}$ | $\mathrm{V}_{\text {I }}=\mathrm{V}_{\text {IH }}$ or $\mathrm{V}_{\text {IL }}$ | $\mathrm{IOH}=-20 \mu \mathrm{~A}$ |  | 4.5 V | 4.4 |  |  | 4.4 |  | 4.4 |  | V |
|  |  | $\mathrm{IOH}=-4 \mathrm{~mA}$ | 3.98 |  |  |  | 3.7 |  | 3.84 |  |  |  |
| VOL | $\mathrm{V}_{\text {I }}=\mathrm{V}_{\text {IH }}$ or $\mathrm{V}_{\text {IL }}$ | $\mathrm{l} \mathrm{OL}=20 \mu \mathrm{~A}$ | 4.5 V |  |  | 0.1 |  | 0.1 |  | 0.1 | V |  |
|  |  | $\mathrm{IOL}=4 \mathrm{~mA}$ |  |  |  | 0.26 |  | 0.4 |  | 0.33 |  |  |
| 1 | $\mathrm{V}_{1}=\mathrm{V}_{\mathrm{CC}}$ to GND |  | 5.5 V |  |  | $\pm 0.1$ |  | $\pm 1$ |  | $\pm 1$ | $\mu \mathrm{A}$ |  |
| ICC | $\mathrm{V}_{\mathrm{I}}=\mathrm{V}_{\text {CC }}$ or $0, \quad \mathrm{I} \mathrm{O}=0$ |  | 5.5 V |  |  | 8 |  | 160 |  | 80 | $\mu \mathrm{A}$ |  |
| ${ }^{\text {I }} \mathrm{CC}{ }^{\dagger}$ | One input at $\mathrm{V}_{\mathrm{CC}}-2.1 \mathrm{~V}$, Other inputs at 0 or $\mathrm{V}_{\mathrm{CC}}$ |  | 4.5 V to 5.5 V |  | 100 | 360 |  | 490 |  | 450 | $\mu \mathrm{A}$ |  |
| $\mathrm{C}_{\mathrm{i}}$ |  |  |  |  |  | 10 |  | 10 |  | 10 | pF |  |

$\dagger$ Additional quiescent supply current per input pin, TTL inputs high, 1 unit load
HCT INPUT LOADING TABLE

| INPUTS | UNIT LOADS |
| :---: | :---: |
| A-D | 0.4 |
| CLK | 1.5 |
| $\overline{\text { LOAD }}$ | 1.5 |
| D/ $\bar{U}$ | 1.2 |
| $\overline{\mathrm{CTEN}}$ | 1.5 |

Unit load is $\mathrm{I}_{\mathrm{CC}}$ limit specified in electrical characteristics table, (e.g., $360 \mu \mathrm{~A}$ max at $25^{\circ} \mathrm{C}$ ).
'HC190, 'HC191 timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 4)

|  |  |  | $\mathrm{V}_{\mathrm{CC}}$ | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ | $\begin{gathered} \mathrm{T}_{\mathrm{A}}=-55^{\circ} \mathrm{C} \\ \mathrm{TO} 125^{\circ} \mathrm{C} \end{gathered}$ | $\begin{gathered} \mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C} \\ \mathrm{TO} 85^{\circ} \mathrm{C} \end{gathered}$ | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | MIN MAX | MIN MAX | MIN MAX |  |
| $\mathrm{f}_{\text {clock }}$ | Clock frequency $\dagger$ |  | 2 V | 6 | 4 | 5 | MHz |
|  |  |  | 4.5 V | 30 | 20 | 25 |  |
|  |  |  | 6 V | 35 | 23 | 29 |  |
| ${ }^{\text {w }}$ w | Pulse duration | $\overline{\text { LOAD }}$ low | 2 V | 80 | 120 | 100 | ns |
|  |  |  | 4.5 V | 16 | 24 | 20 |  |
|  |  |  | 6 V | 14 | 20 | 17 |  |
|  |  | CLK high or low | 2 V | 100 | 150 | 125 |  |
|  |  |  | 4.5 V | 20 | 30 | 25 |  |
|  |  |  | 6 V | 17 | 26 | 21 |  |
| ${ }_{\text {tsu }}$ | Setup time | Data before $\overline{\text { LOAD } \uparrow}$ | 2 V | 60 | 90 | 75 | ns |
|  |  |  | 4.5 V | 12 | 18 | 15 |  |
|  |  |  | 6 V | 10 | 15 | 13 |  |
|  |  | $\overline{\text { CTEN }}$ before CLK $\uparrow$ | 2 V | 60 | 90 | 75 |  |
|  |  |  | 4.5 V | 12 | 18 | 15 |  |
|  |  |  | 6 V | 10 | 15 | 13 |  |
|  |  | D/U before CLK $\uparrow$ | 2 V | 90 | 135 | 115 |  |
|  |  |  | 4.5 V | 18 | 27 | 23 |  |
|  |  |  | 6 V | 15 | 23 | 20 |  |
| $t_{\text {h }}$ | Hold time | Data before $\overline{\text { LOAD } \uparrow}$ | 2 V | 2 | 2 | 2 | ns |
|  |  |  | 4.5 V | 2 | 2 | 2 |  |
|  |  |  | 6 V | 2 | 2 | 2 |  |
|  |  | $\overline{\text { CTEN }}$ before CLK $\uparrow$ | 2 V | 2 | 2 | 2 |  |
|  |  |  | 4.5 V | 2 | 2 | 2 |  |
|  |  |  | 6 V | 2 | 2 | 2 |  |
|  |  | D/U before CLK $\uparrow$ | 2 V | 0 | 0 | 0 |  |
|  |  |  | 4.5 V | 0 | 0 | 0 |  |
|  |  |  | 6 V | 0 | 0 | 0 |  |
| trec | Recovery time | $\overline{\text { LOAD }}$ inactive before CLK $\uparrow$ | 2 V | 60 | 90 | 75 | ns |
|  |  |  | 4.5 V | 12 | 18 | 15 |  |
|  |  |  | 6 V | 10 | 15 | 13 |  |

$\dagger$ Applies to noncascaded operation only. With cascaded counters, clock-to-terminal count propagation delays, $\overline{\text { CTEN }}$-to-clock setup times, and $\overline{\text { CTEN }}$-to-clock hold times determine maximum clock frequency. For example, with these HC devices:

'HC190, 'HC191
switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 4)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | LOAD CAPACITANCE | $\mathrm{V}_{\mathrm{cc}}$ | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ |  | $\begin{gathered} \mathrm{T}_{\mathrm{A}}=-55^{\circ} \mathrm{C} \\ \mathrm{TO} 125^{\circ} \mathrm{C} \end{gathered}$ | $\begin{gathered} \mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C} \\ \mathrm{TO} 85^{\circ} \mathrm{C} \end{gathered}$ | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  |  | MIN | TYP MAX | MIN MAX | MIN MAX |  |
| ${ }_{\text {f max }}$ |  |  |  | 2 V | 6 |  | 4 | 5 | MHz |
|  |  |  |  | 4.5 V | 30 |  | 20 | 25 |  |
|  |  |  |  | 6 V | 35 |  | 23 | 29 |  |
| $t_{\text {tpd }}$ | $\overline{\text { LOAD }}$ | Q | $C_{L}=50 \mathrm{pF}$ | 2 V |  | 195 | 295 | 245 | ns |
|  |  |  |  | 4.5 V |  | 39 | 59 | 49 |  |
|  |  |  |  | 6 V |  | 33 | 50 | 42 |  |
|  |  |  | $\mathrm{C}_{\mathrm{L}}=15 \mathrm{pF}$ | 5 V |  | 16 |  |  |  |
|  | $\begin{gathered} \text { A, B, C, } \\ \text { or D } \end{gathered}$ | Q | $C_{L}=50 \mathrm{pF}$ | 2 V |  | 175 | 265 | 220 |  |
|  |  |  |  | 4.5 V |  | 35 | 53 | 44 |  |
|  |  |  |  | 6 V |  | 30 | 45 | 37 |  |
|  |  |  | $C_{L}=15 \mathrm{pF}$ | 5 V |  | 14 |  |  |  |
|  | CLK | Q | $C_{L}=50 \mathrm{pF}$ | 2 V |  | 170 | 255 | 215 |  |
|  |  |  |  | 4.5 V |  | 34 | 51 | 43 |  |
|  |  |  |  | 6 V |  | 29 | 43 | 37 |  |
|  |  |  | $C_{L}=15 \mathrm{pF}$ | 5 V |  | 14 |  |  |  |
|  | CLK | $\overline{\mathrm{RCO}}$ | $C_{L}=50 \mathrm{pF}$ | 2 V |  | 125 | 190 | 155 |  |
|  |  |  |  | 4.5 V |  | 25 | 38 | 31 |  |
|  |  |  |  | 6 V |  | 21 | 32 | 26 |  |
|  |  |  | $C_{L}=15 \mathrm{pF}$ | 5 V |  | 10 |  |  |  |
|  | CLK | MAX/MIN | $C_{L}=50 \mathrm{pF}$ | 2 V |  | 210 | 315 | 265 |  |
|  |  |  |  | 4.5 V |  | 42 | 63 | 53 |  |
|  |  |  |  | 6 V |  | 36 | 54 | 45 |  |
|  |  |  | $\mathrm{C}_{\mathrm{L}}=15 \mathrm{pF}$ | 5 V |  | 18 |  |  |  |
|  | D/U | $\overline{\mathrm{RCO}}$ | $C_{L}=50 \mathrm{pF}$ | 2 V |  | 150 | 225 | 190 |  |
|  |  |  |  | 4.5 V |  | 30 | 45 | 38 |  |
|  |  |  |  | 6 V |  | 26 | 38 | 33 |  |
|  |  |  | $C_{L}=15 \mathrm{pF}$ | 5 V |  | 12 |  |  |  |
|  | D/U | MAX/MIN | $C_{L}=50 \mathrm{pF}$ | 2 V |  | 165 | 250 | 205 |  |
|  |  |  |  | 4.5 V |  | 33 | 50 | 41 |  |
|  |  |  |  | 6 V |  | 28 | 43 | 35 |  |
|  |  |  | $C_{L}=15 \mathrm{pF}$ | 5 V |  | 13 |  |  |  |
|  | $\overline{\text { CTEN }}$ | $\overline{\mathrm{RCO}}$ | $C_{L}=50 \mathrm{pF}$ | 2 V |  | 125 | 190 | 155 |  |
|  |  |  |  | 4.5 V |  | 25 | 38 | 31 |  |
|  |  |  |  | 6 V |  | 21 | 32 | 26 |  |
|  |  |  | $\mathrm{C}_{\mathrm{L}}=15 \mathrm{pF}$ | 5 V |  | 10 |  |  |  |
| $t_{t}$ |  | Any | $C_{L}=50 \mathrm{pF}$ | 2 V |  | 75 | 110 | 95 | ns |
|  |  |  |  | 4.5 V |  | 15 | 22 | 19 |  |
|  |  |  |  | 6 V |  | 13 | 19 | 16 |  |

'HCT191
timing requirements over recommended operating free-air temperature range $\mathrm{V}_{\mathrm{CC}}=4.5 \mathrm{~V}$ (unless otherwise noted) (see Figure 5)


## 'HCT191

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 5)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | LOAD CAPACITANCE | $\mathrm{V}_{\mathrm{Cc}}$ | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ |  | $\begin{gathered} \mathrm{T}_{\mathrm{A}}=-55^{\circ} \mathrm{C} \\ \mathrm{TO} 125^{\circ} \mathrm{C} \end{gathered}$ | $\begin{gathered} \mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C} \\ \mathrm{TO} 85^{\circ} \mathrm{C} \end{gathered}$ | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  |  | MIN | TYP MAX | MIN MAX | MIN MAX |  |
| ${ }_{\text {f max }}$ |  |  |  | 4.5 V | 30 |  | 20 | 25 | MHz |
| $t_{\text {pd }}$ | $\overline{\text { LOAD }}$ | Q | $\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}$ | 4.5 V |  | 40 | 60 | 50 | ns |
|  |  |  | $\mathrm{CL}_{\mathrm{L}}=15 \mathrm{pF}$ | 5 V |  | 17 |  |  |  |
|  | $\begin{gathered} \text { A, B, C, } \\ \text { or D } \end{gathered}$ | Q | $\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}$ | 4.5 V |  | 38 | 57 | 48 |  |
|  |  |  | $\mathrm{C}_{\mathrm{L}}=15 \mathrm{pF}$ | 5 V |  | 16 |  |  |  |
|  | CLK | $\overline{\mathrm{RCO}}$ | $\mathrm{CL}_{\mathrm{L}}=50 \mathrm{pF}$ | 4.5 V |  | 35 | 53 | 44 |  |
|  |  |  | $\mathrm{C}_{\mathrm{L}}=15 \mathrm{pF}$ | 5 V |  | 14 |  |  |  |
|  | CLK | Q | $\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}$ | 4.5 V |  | 27 | 41 | 34 |  |
|  |  |  | $\mathrm{C}_{\mathrm{L}}=15 \mathrm{pF}$ | 5 V |  | 11 |  |  |  |
|  | CLK | MAX/MIN | $\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}$ | 4.5 V |  | 42 | 63 | 53 |  |
|  |  |  | $\mathrm{C}_{\mathrm{L}}=15 \mathrm{pF}$ | 5 V |  | 18 |  |  |  |
|  | D/Ū | $\overline{\mathrm{RCO}}$ | $\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}$ | 4.5 V |  | 30 | 45 | 38 |  |
|  |  |  | $\mathrm{C}_{\mathrm{L}}=15 \mathrm{pF}$ | 5 V |  | 12 |  |  |  |
|  | D/U | MAX/MIN | $\mathrm{CLL}_{\mathrm{L}}=50 \mathrm{pF}$ | 4.5 V |  | 38 | 57 | 48 |  |
|  |  |  | $\mathrm{C}_{\mathrm{L}}=15 \mathrm{pF}$ | 5 V |  | 16 |  |  |  |
|  | $\overline{\text { CTEN }}$ | $\overline{\mathrm{RCO}}$ | $\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}$ | 4.5 V |  | 27 | 41 | 34 |  |
|  |  |  | $\mathrm{C}_{\mathrm{L}}=15 \mathrm{pF}$ | 5 V |  | 11 |  |  |  |
| $t_{t}$ |  | Any | $\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}$ | 4.5 V |  | 15 | 22 | 19 | ns |

CD54HC191, CD74HC191, CD54HCT191, CD74HCT191
SYNCHRONOUS UP/DOWN COUNTERS WITH DOWN/UP MODE CONTROL
SCHS275E - MARCH 2002 - REVISED OCTOBER 2003
operating characteristics, $\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$

| PARAMETER |  |  | TYP | UNIT |
| :---: | :---: | :---: | :---: | :---: |
|  | Power dissipation capacitance | 'HC190 | 59 | pF |
|  |  | 'HC191 | 55 |  |
|  |  | 'HCT191 | 68 |  |

## PARAMETER MEASUREMENT INFORMATION - 'HC190, 'HC191



LOAD CIRCUIT



VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

| PARAMETER |  | S1 | S2 |
| :--- | :---: | :---: | :---: |
| $\mathrm{t}_{\text {en }}$ | t PZH | Open | Closed |
|  | tpZL | Closed | Open |
| $\mathrm{t}_{\text {dis }}$ | $\mathrm{t}_{\text {PHZ }}$ | Open | Closed |
|  | $\mathrm{t}_{\text {PLZ }}$ | Closed | Open |
| $\mathrm{t}_{\text {pd }}$ or $\mathrm{t}_{\mathrm{t}}$ |  |  | Open |


VOLTAGE WAVEFORMS SETUP AND HOLD AND INPUT RISE AND FALL TIMES


VOLTAGE WAVEFORMS OUTPUT ENABLE AND DISABLE TIMES

NOTES: A. $C_{L}$ includes probe and test-fixture capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $\mathrm{PRR} \leq 1 \mathrm{MHz}, \mathrm{Z}_{\mathrm{O}}=50 \Omega, \mathrm{t}_{\mathrm{r}}=6 \mathrm{~ns}, \mathrm{t}_{\mathrm{f}}=6 \mathrm{~ns}$.
D. For clock inputs, $f_{\max }$ is measured with the input duty cycle at $50 \%$.
E. The outputs are measured one at a time with one input transition per measurement.
F. $t_{P L Z}$ and $t P H Z$ are the same as $t_{\text {dis }}$.
G. $t_{P Z L}$ and $t_{P Z H}$ are the same as ten.
H. tPLH and tPHL are the same as $t_{p d}$.

Figure 4. Load Circuit and Voltage Waveforms

## PARAMETER MEASUREMENT INFORMATION - 'HCT191



LOAD CIRCUIT


VOLTAGE WAVEFORMS RECOVERY TIME


VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

| PARAMETER |  | S1 | S2 |
| :---: | :---: | :---: | :---: |
| ten | tPZH | Open | Closed |
|  | tPZL | Closed | Open |
| $t_{\text {dis }}$ | tPHZ | Open | Closed |
|  | tpLZ | Closed | Open |
| $\mathrm{t}_{\mathrm{pd}}$ or $\mathrm{t}_{\mathrm{t}}$ |  | Open | Open |




NOTES: A. $C_{L}$ includes probe and test-fixture capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $\mathrm{PRR} \leq 1 \mathrm{MHz}, \mathrm{Z}_{\mathrm{O}}=50 \Omega, \mathrm{t}_{\mathrm{r}}=6 \mathrm{~ns}, \mathrm{t}_{\mathrm{f}}=6 \mathrm{~ns}$.
D. For clock inputs, $f_{\max }$ is measured with the input duty cycle at $50 \%$.
E. The outputs are measured one at a time with one input transition per measurement.
F. tpLZ and tPHZ are the same as $\mathrm{t}_{\text {dis }}$.
G. tpZL and tpZH are the same as ten.
H. tPLH and tPHL are the same as tpd

Figure 5. Load Circuit and Voltage Waveforms INSTRUMENTS
www.ti.com

## PACKAGING INFORMATION

| Orderable Device | Status <br> (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <br> (2) | Lead/Ball Finish <br> (6) | MSL Peak Temp <br> (3) | Op Temp ( ${ }^{\circ} \mathrm{C}$ ) | Device Marking <br> (4/5) | Samples |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 5962-8867101EA | ACTIVE | CDIP | $J$ | 16 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | $\begin{aligned} & \text { 5962-8867101EA } \\ & \text { CD54HCT191F3A } \end{aligned}$ | Samples |
| 5962-8994601EA | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-8994601EA CD54HC190F3A | Samples |
| CD54HC190F3A | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N/ A for Pkg Type | -55 to 125 | $\begin{aligned} & \text { 5962-8994601EA } \\ & \text { CD54HC190F3A } \end{aligned}$ | Samples |
| CD54HC191F3A | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N/ A for Pkg Type | -55 to 125 | $\begin{aligned} & \text { 5962-8689101EA } \\ & \text { CD54HC191F3A } \end{aligned}$ | Samples |
| CD54HCT191F3A | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N/ A for Pkg Type | -55 to 125 | $\begin{aligned} & \text { 5962-8867101EA } \\ & \text { CD54HCT191F3A } \end{aligned}$ | Samples |
| CD74HC190E | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N/ A for Pkg Type | -55 to 125 | CD74HC190E | Samples |
| CD74HC190EE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N/ A for Pkg Type | -55 to 125 | CD74HC190E | Samples |
| CD74HC190NSR | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS \& no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC190M | Samples |
| CD74HC190PW | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS \& no $\mathrm{Sb} / \mathrm{Br}$ ) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HJ190 | Samples |
| CD74HC190PWR | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS \& no $\mathrm{Sb} / \mathrm{Br}$ ) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HJ190 | Samples |
| CD74HC191E | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N/ A for Pkg Type | -55 to 125 | CD74HC191E | Samples |
| CD74HC191EE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N/A for Pkg Type | -55 to 125 | CD74HC191E | Samples |
| CD74HC191M | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS \& no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC191M | Samples |
| CD74HC191M96 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS \& no $\mathrm{Sb} / \mathrm{Br}$ ) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC191M | Samples |
| CD74HC191M96E4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS \& no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC191M | Samples |
| CD74HC191MG4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS \& no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC191M | Samples |
| CD74HC191MT | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS \& no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC191M | Samples |


| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <br> (2) | Lead/Ball Finish <br> (6) | MSL Peak Temp <br> (3) | Op Temp ( ${ }^{\circ} \mathrm{C}$ ) | Device Marking <br> (4/5) | Samples |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| CD74HCT191E | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD74HCT191E | Samples |
| CD74HCT191M | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS \& no $\mathrm{Sb} / \mathrm{Br}$ ) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HCT191M | Samples |

${ }^{(1)}$ The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.
${ }^{(2)}$ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS \& no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): Tl's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed $0.1 \%$ by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb -Free (RoHS compatible) as defined above.
Green (RoHS \& no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed $0.1 \%$ by weight in homogeneous material)
${ }^{(3)}$ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
${ }^{(4)}$ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device
${ }^{(5)}$ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
${ }^{(6)}$ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF CD54HC190, CD54HC191, CD54HCT191, CD74HC190, CD74HC191, CD74HCT191 :

- Catalog: CD74HC190, CD74HC191, CD74HCT191
- Military: CD54HC190, CD54HC191, CD54HCT191

NOTE: Qualified Version Definitions:
-Catalog - Tl's standard catalog product

- Military - QML certified for Military and Defense Applications


## TAPE AND REEL INFORMATION


*All dimensions are nominal

| Device | Package <br> Type | Package <br> Drawing | Pins | SPQ | Reel <br> Diameter <br> $(\mathbf{m m})$ | Reel <br> Width <br> $\mathbf{W 1}(\mathbf{m m})$ | A0 <br> $(\mathbf{m m})$ | B0 <br> $(\mathbf{m m})$ | K0 <br> $(\mathbf{m m})$ | P1 <br> $(\mathbf{m m})$ | W <br> $(\mathbf{m m})$ | Pin1 <br> Quadrant |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| CD74HC190NSR | SO | NS | 16 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| CD74HC190PWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| CD74HC191M96 | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| CD74HC190NSR | SO | NS | 16 | 2000 | 367.0 | 367.0 | 38.0 |
| CD74HC190PWR | TSSOP | PW | 16 | 2000 | 367.0 | 367.0 | 35.0 |
| CD74HC191M96 | SOIC | D | 16 | 2500 | 333.2 | 345.9 | 28.6 |

D (R-PDSO-G16)


NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.

C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed $0.006(0,15)$ each side.
D Body width does not include interlead flash. Interlead flash shall not exceed $0.017(0,43)$ each side.
E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)


NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC-7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

NS (R-PDSO-G**)
14-PINS SHOWN


| DIM PINS ** | 14 | 16 | 20 | 24 |
| :---: | :---: | :---: | :---: | :---: |
| A MAX | 10,50 | 10,50 | 12,90 | 15,30 |
| A MIN | 9,90 | 9,90 | 12,30 | 14,70 |

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.


| DIM PINS ** | 14 | 16 | 18 | 20 |
| :---: | :---: | :---: | :---: | :---: |
| A | 0.300 <br> $(7,62)$ <br> BSC | 0.300 <br> $(7,62)$ <br> BSC | 0.300 <br> $(7,62)$ <br> BSC | 0.300 <br> $(7,62)$ <br> BSC |
| B MAX | 0.785 <br> $(19,94)$ | .840 <br> $(21,34)$ | 0.960 <br> $(24,38)$ | 1.060 <br> $(26,92)$ |
| B MIN | - | - | - | - |
| C MAX | 0.300 <br> $(7,62)$ | 0.300 <br> $(7,62)$ | 0.310 <br> $(7,87)$ | 0.300 <br> $(7,62)$ |
| C MIN | 0.245 <br> $(6,22)$ | 0.245 <br> $(6,22)$ | 0.220 <br> $(5,59)$ | 0.245 <br> $(6,22)$ |



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

PW (R-PDSO-G16)


NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
B. This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
D Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
E. Falls within JEDEC MO-153


NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC-7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T**)
PLASTIC DUAL-IN-LINE PACKAGE
16 PINS SHOWN


NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C) Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

D The 20 pin end lead shoulder width is a vendor option, either half or full width.

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[^0]:    $\mathrm{D} / \overline{\mathrm{U}}$ or $\overline{\mathrm{CTEN}}$ should be changed only when clock is high.
    X = Don't care
    」Low-to-high clock transition

